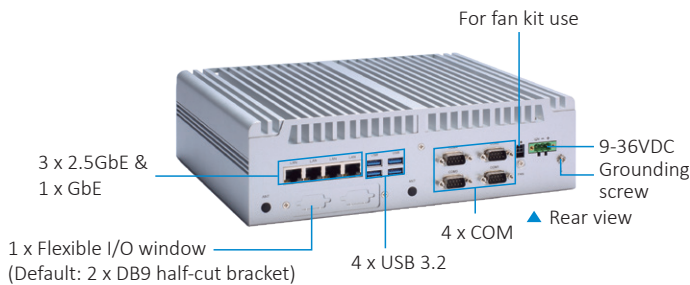
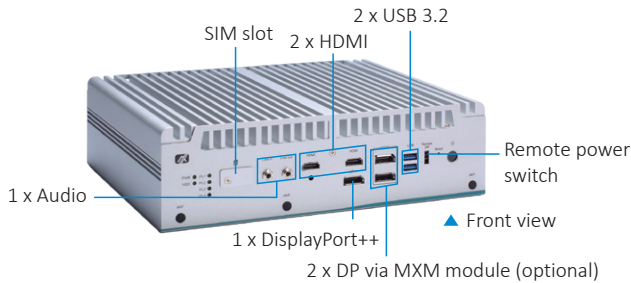


eBOX671B NEW

Fanless Embedded System with LGA1700 Socket 13th/12th Gen Intel® Core™ i9/i7/i5/i3 or Celeron® Processor, Intel® R680E, 2 HDMI, 1 DisplayPort, 6 USB, 4 LANs, MXM 3.1 Type A, and 9 to 36 VDC

Features

- 13th/12th Gen Intel® Core™ i9/i7/i5/i3 and Celeron® processors with Intel® R680E chipset (Alder Lake S)
- Dual DDR5 SO-DIMM for up to 64GB of memory
- 4 LAN with optional PoE supported
- Dual 2.5" SATA SSD/HDD drive bays with RAID 0 & 1
- High speed NVMe storage (M.2 2280) supported
- Supports MXM 3.1 Type A, up to 5 display outputs
- -40 °C to +65 °C wide operating temperatures
- Wide range power input from 9 to 36 VDC
- Flexible I/O window supported via mPCIe modules



Specifications

Standard Color	Silver		
Construction	Aluminum extrusion and heavy-duty steel, IP40		
CPU	LGA1700 socket 13th/12th Gen Intel® Core™ i9/i7/i5/i3 & Celeron® processor (35W/65W)		
System Memory	2 x 262-pin DDR5-4800 SO-DIMM, up to 64GB		
Chipset	Intel® R680E		
BIOS	AMI		
System I/O Outlet	<table border="0" style="width: 100%;"> <tr> <td style="width: 50%; vertical-align: top;"> Front side 2 x HDMI 1.4b (1 x lockable) 1 x DisplayPort 1.2a 2 x DisplayPort 1.4a via optional MXM kit 2 x USB 3.2 Gen2 1 x Power button 1 x Remote switch 1 x Front access SIM slot with cover (for M.2 Key B) 1 x Reset switch connector 3 x Antenna opening 1 x Audio (MIC-in/Line-out) </td> <td style="width: 50%; vertical-align: top;"> Rear side 4 x USB 3.2 Gen2 3 x 2.5 GbE* LAN (Intel® I226-IT) 1 x GbE* LAN (Intel® I219-LM) *4 x PoE by option (IEEE802.3at, up to 60W) 2 x RS-232/422/485 with autoflow 2 x RS-232 1 x Phoenix type VDC power input connector 1 x Flexible IO window (Default: 2 x DB9 half-cut bracket) 1 x Grounding screw 2 x Antenna opening </td> </tr> </table>	Front side 2 x HDMI 1.4b (1 x lockable) 1 x DisplayPort 1.2a 2 x DisplayPort 1.4a via optional MXM kit 2 x USB 3.2 Gen2 1 x Power button 1 x Remote switch 1 x Front access SIM slot with cover (for M.2 Key B) 1 x Reset switch connector 3 x Antenna opening 1 x Audio (MIC-in/Line-out)	Rear side 4 x USB 3.2 Gen2 3 x 2.5 GbE* LAN (Intel® I226-IT) 1 x GbE* LAN (Intel® I219-LM) *4 x PoE by option (IEEE802.3at, up to 60W) 2 x RS-232/422/485 with autoflow 2 x RS-232 1 x Phoenix type VDC power input connector 1 x Flexible IO window (Default: 2 x DB9 half-cut bracket) 1 x Grounding screw 2 x Antenna opening
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Watchdog Timer	255 levels, 1 to 255 sec.		
Storage	2 x 2.5" SATA HDD/SSD (up to 15 mm height; RAID 0,1 supported) 1 x NVMe by M.2 Key M 2280 1 x mSATA (enable in BIOS setting)		
Expansion Interface	1 x Full-size PCI Express Mini Card slot (USB 2.0 + PCIe + SIM + mSATA signal) 1 x M.2 Key M 2280 socket (for storage) (PCIe x4 signal) 1 x M.2 Key E 2230 socket (for Wi-Fi 6E) (USB 2.0 signal) 1 x M.2 Key B 3052 socket (for 5G) (PCIex2 signal) 1 x Internal SIM slot for PCIe Mini Card slot 1 x MXM3.1 type A connector		
TPM	TPM 2.0		

Specifications

System Indicator	1 x Green LED for system power 1 x Orange LED for HDD active 4 x Programmable Green LED
Power Input	9 to 36VDC with ignition for standard Optional PoE function only supports 24V DC input
Operating Temperature	Without MXM module (for CPU 35W/65W): -40°C to +65°C (-40°F to +140°F) (with W.T. DRAM & SSD) With MXM module (only for CPU 35W)(For W.T. MXM T1000 & A500): -40°C to +50°C (-40°F to +122°F) (with W.T. DRAM & SSD) With MXM module (only for CPU 35W) (For W.T. MXM A2000 and must with optional fan kit): -40°C to +50°C (-40°F to +122°F) (with W.T. DRAM & SSD)
Humidity	10% - 90%, non-condensing
Shock Vibration	IEC 60068-2-27 (w/ SSD: 50G, half-sine, 11 ms duration)
Vibration Endurance	IEC 60068-2-64 (w/ SSD: 3Grms STD, random, 5- 500 Hz, 1 hr/axis)
Dimensions	280 mm (11.02") (W) x 210 mm (8.26") (D) x 80.5 mm (3.16") (H)
Weight (net/gross)	4.2 kg (9.25 lb)/5 kg (11.02 lb)
Certifications	CE, FCC Class A, UKCA
EOS Support	Win 10 IoT, Win 11 IoT, Linux

* W.T.: Wide Temperature. All W.T. supported products have to be sorted by Axiomtek.

Packing List

- 1 x Thermal grease
- 1 x 3-pin terminal block connector
- 1 x Remote power switch cable
- 4 x Foot pad
- 2 x HDD bracket
- 1 x Screw Pack
- 2 x DRAM thermal pad

Power Protection

DC Version

- OVP (over voltage protection)
- UVP (under voltage protection)
- OCP (over current protection)
- SCP (short circuit protection)
- Reverse protection

Ordering Information

Standard

eBOX671B-ALD-GbE (P/N: E36K671B00)	Fanless embedded system with LGA1700 socket 13th/12th Gen Intel® Core™ i9/i7/i5/i3 or Celeron® processor, Intel® R680E, 2 HDMI, 1 DisplayPort, 6 USB, 4 LANs, and 9 to 36 VDC
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Optional

2.5" SATA HDD	80GB or above
2.5" SATA SSD	100GB or above
DDR5 SO-DIMM	8GB to 32GB
mSATA	64GB or above
8816K6718A0E	Wall mount kit
886K671A0A0E	DIN-rail kit
	Wi-Fi/LTE module
509000001500	24V 120W power adapter Power cord
E392903102	AX92903 CANbus PCI Express Mini module
E392902103	AX92902 LAN PCI Express Mini module
E392918103	AX92918 Dual LAN PCI Express Mini module
	Fan kit
	NVIDIA RTX™ A2000 MXM module
	NVIDIA RTX™ A500 MXM module
	NVIDIA RTX™ T1000 MXM module

* Specifications and certifications may vary based on different requirements.

Dimensions

